4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6A Output Current

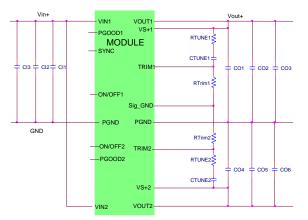
**RoHS Compliant** 





## **Applications**

- Distributed power architectures
- Intermediate bus voltage applications
- Telecommunications equipment
- Servers and storage applications
- Networking equipment
- Industrial equipment



### **Features**

- Compliant to RoHS Directive 2011/65/EU and amended Directive (EU) 2015/863.
- Compliant to IPC-9592 (September 2008), Category 2, Class II
- Compatible in a Pb-free or SnPb reflow environment (Z versions)
- Compliant to REACH Directive (EC) No 1907/2006
- Wide Input voltage range (4.5Vdc-14.4Vdc) on both inputs
- Each Output voltage programmable from 0.6Vdc to 5.5Vdc via external resistor.
- Tunable Loop<sup>™</sup> to optimize dynamic output voltage response
- Power Good signal for each output
- Fixed switching frequency with capability of external synchronization
- 180° Out-of-phase inputs to reduce input ripple
- Output overcurrent protection (non-latching)
- Output Overvoltage protection
- Over temperature protection
- Remote On/Off
- Ability to sink and source current
- Start up into Pre-biased output
- Cost efficient open frame design
- Small size: 20.32 mm x 11.43 mm x 8.5 mm (0.8 in x 0.45 in x 0.335 in)
- Wide operating temperature range [-40°C to 105°C(Ruggedized: -D), 85°C(Regular)]
- Ruggedized (-D) version able to withstand high levels of shock and vibration
- ANSI/UL\* 62368-1 and CAN/CSA<sup>†</sup> C22.2 No. 62368-1 Recognized, DIN VDE<sup>‡</sup> 0868-1/A11:2017 (EN62368-1:2014/A11:2017)
- ISO\*\* 9001 and ISO 14001 certified manufacturing facilities

## Description

The 2 × 6A Analog Dual MicroDlynx<sup>TM</sup> power modules are non-isolated dc-dc converters that can deliver up to 2 × 6A of output current. These modules operate over a wide range of input voltage ( $V_{IN}$  = 4.5Vdc-14.4Vdc) and provide precisely regulated output voltages from 0.6Vdc to 5.5Vdc. Features include remote On/Off, adjustable output voltage, over current and over temperature protection. The module also includes the Tunable Loop<sup>TM</sup> feature that allows the user to optimize the dynamic response of the converter to match the load with reduced amount of output capacitance leading to savings on cost and PWB area.

\* UL is a registered trademark of Underwriters Laboratories, Inc.

- <sup>+</sup> CSA is a registered trademark of Canadian Standards Association.
- <sup>‡</sup> VDE is a trademark of Verband Deutscher Elektrotechniker e.V.
  \*\* ISO is a registered trademark of the International Organization of Standards



4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6A Output Current

## **Absolute Maximum Ratings**

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. These are absolute stress ratings only, functional operation of the device is not implied at these or any other conditions in excess of those given in the operations sections of the data sheet. Exposure to absolute maximum ratings for extended periods can adversely affect the device reliability.

Parameter	Device	Symbol	Min	Max	Unit
Input Voltage	All	$V_{\text{IN1}}  and  V_{\text{IN2}}$	-0.3	15	V
Continuous					
VS+1, VS+2,	All		-0.3	7	V
Operating Ambient Temperature	All	TA	-40	85	°C
(see Thermal Considerations section)	-D Version	TA	-40	105	°C
Storage Temperature	All	T <sub>stg</sub>	-55	125	°C

## **Electrical Specifications**

Unless otherwise indicated, specifications apply over all operating input voltage, resistive load, and temperature conditions.

Parameter	Device	Symbol	Min	Тур	Max	Unit
Operating Input Voltage	All	$V_{\text{IN1}}$ and $V_{\text{IN2}}$	4.5	_	14.4	Vdc
Maximum Input Current	All	I <sub>IN1,max</sub> & I <sub>IN2,max</sub>			12	Adc
$(V_{IN}=3V \text{ to } 14.4V, I_0=I_{O, max})$						
Input No Load Current	V <sub>O,set</sub> = 0.6 Vdc	I <sub>IN1,No</sub> load &		40		mA
( $V_{IN}$ = 12Vdc, $I_0$ = 0, module enabled)	V <sub>O,set</sub> = 5.5Vdc	I <sub>IN,1No load</sub> & I <sub>IN2,No load</sub>		140		mA
Input Stand-by Current (V <sub>IN</sub> = 12Vdc, module disabled)	All	I <sub>IN1,stand-by</sub> & I <sub>IN2,stand-by</sub>		14		mA
Inrush Transient	All	$I_1^2 t \& I_2^2 t$			1	A <sup>2</sup> s
Input Reflected Ripple Current, peak-to-peak (5Hz to 20MHz, 1µH source impedance; $V_{IN}$ =4.5 to 14V, $I_0 = I_{Omax}$ ; See Test Configurations)	All	Both Inputs		25		mAp-p
Input Ripple Rejection (120Hz)	All	Both Inputs		-68		dB

4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6A Output Current

## Electrical Specifications (continued)

Parameter	Device	Symbol	Min	Тур	Max	Unit
Output Voltage Set-point (with 0.1% tolerance for external resistor used to set output voltage)	All	VO1, set & VO2, set	-1.0		+1.0	% VO, set
Output Voltage (Over all operating input voltage, resistive load, and temperature conditions until end of life)	All	Vo1, set & VO2, set	-3.0		+3.0	% VO, set
Adjustment Range (selected by an external resistor) (Some output voltages may not be possible depending on the input voltage – see Feature Descriptions Section)	All	VO1 & VO2	0.6		5.5	Vdc
Remote Sense Range	All	Both outputs			0.5	Vdc
Output Regulation (for $V_0 \ge 2.5Vdc$ )		Both Outputs				
Line (V <sub>IN</sub> =V <sub>IN, min</sub> to V <sub>IN, max</sub> )	All	Both Outputs		—	+0.4	% V <sub>O, set</sub>
Load (Io=Io, min to Io, max)	All	Both Outputs		_	10	mV
Output Regulation (for Vo< 2.5Vdc)						
Line (V <sub>IN</sub> =V <sub>IN, min</sub> to V <sub>IN, max</sub> )	All	Both Outputs		_	5	mV
Load $(I_0=I_{O, min} \text{ to } I_{O, max})$	All	Both Outputs		_	10	mV
Temperature ( $T_{ref}=T_{A, min}$ to $T_{A, max}$ )	All	Both Outputs		_	0.4	% V <sub>O, set</sub>
Input Noise on nominal output at 25°C (VIN=VIN, nom and IO=IO, min to IO, max Cin = 2x1x4.7nF(or equiv.) + 2x2x22uFceramic + 2x470uFelectrolytic Peak-to-Peak (Full Bandwidth)	All	Both Inputs		360		mVpk-pk
Output Ripple and Noise on nominal output at 25°C	7.11	Botti inputs		500		ттркр
$(V_{IN}=V_{IN, nom} \text{ and } I_O=I_O, min \text{ to } I_O, max \text{ Co} = 2\times4.7 \text{nF} + 2\times47 \text{uF per output})$						
Peak-to-Peak (5Hz to 20MHz bandwidth)	All		_	50		mV <sub>pk-pk</sub>
RMS (5Hz to 20MHz bandwidth)	All			30		mV <sub>rms</sub>
Output Ripple and Noise on nominal output at 25°C (VIN=VIN, nom and IO=IO, min to IO, max Co = 2x4.7nF (or equiv) + 2x47uF per output) Peak-to-Peak (Full bandwidth)(Vo≤1.2Vo)		Both Outputs		30		mVpk-pl
Peak-to-Peak (Full bandwidth)(Vo>1.2Vo) RMS (Full bandwidth)	All	Both Outputs Both Outputs		3%Vo 30		mVpk-pl mVrms
External Capacitance <sup>1</sup>	7.11	Both Outputs		50		
Without the Tunable Loop <sup>™</sup>						
ESR ≥ 1 mΩ	All	C <sub>O, max</sub>	1×47		2×47	μF
With the Tunable Loop™						F.
$\text{ESR} \ge 0.15 \text{ m}\Omega$	All	C <sub>O, max</sub>		_	1000	μF
$ESR \ge 10 \text{ m}\Omega$	All	Co, max		_	5000	μF
Output Current (in either sink or source mode)	All	l <sub>o</sub>	0		6 x 2	Adc
Output Current Limit Inception (Hiccup Mode) (current limit does not operate in sink mode)	All	Io, lim		150	-	% I <sub>o,max</sub>
	A.II.			-		Arms
Output Short-Circuit Current	All	101, s/c , 101, s/c		5		AIIIIS

<sup>1</sup> External capacitors may require using the new Tunable Loop<sup>™</sup> feature to ensure that the module is stable as well as getting the best transient response. See the Tunable Loop<sup>™</sup> section for details.

4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6AOutput Current

## Electrical Specifications (continued)

Parameter	Device	Symbol	Min	Тур	Max	Unit
Efficiency	V <sub>O,set</sub> = 0.6Vdc	η 1, η 2		79.3		%
V <sub>IN</sub> = 12Vdc, T <sub>A</sub> =25°C	V <sub>O, set</sub> = 1.2Vdc	η 1, η 2		87.3		%
I <sub>O</sub> =I <sub>O, max</sub> , V <sub>O</sub> = V <sub>O,set</sub>	V <sub>O,set</sub> = 1.8Vdc	η 1, η 2		90.3		%
	V <sub>O,set</sub> = 2.5Vdc	η 1, η 2		92.1		%
	V <sub>o, set</sub> = 3.3Vdc	η 1, η 2		93.3		%
	V <sub>O,set</sub> = 5.0Vdc	η 1, η 2		94.8		%
Switching Frequency	All	f <sub>sw</sub>		500		kHz
Frequency Synchronization	All					
Synch Frequency (2 x f <sub>switch</sub> )				1000		kHz
Synchronization Frequency Range	All		-5%		+5%	kHz
High-Level Input Voltage	All	VIH	2.0			V
Low-Level Input Voltage	All	VIL			0.4	V
Minimum Pulse Width, SYNC	All	tSYNC	100			ns
Maximum SYNC rise time	All	tSYNC_SH			100	ns

## **General Specifications**

Parameter	Device	Min	Тур	Max	Unit
Calculated MTBF ( $I_0$ =0.8 $I_{0, max}$ , $T_A$ =40°C) Telecordia Issue 3 Method 1 Case 3	All		87,926,219		Hours
Weight		—	4.5 (0.16)		g (oz.)

## **Feature Specifications**

Unless otherwise indicated, specifications apply over all operating input voltage, resistive load, and temperature conditions. See Feature Descriptions for additional information.

Parameter	Device	Symbol	Min	Тур	Max	Unit
On/Off Signal Interface						
( $V_{IN}=V_{IN, min}$ to $V_{IN, max}$ ; open collector or equivalent,						
Signal referenced to GND)						
Device Code with no suffix – Negative Logic (See Ordering Information) (On/OFF pin is open collector/drain logic input with						
external pull-up resistor; signal referenced to GND)						
Logic High (Module OFF)						
Input High Current	All	Іін1, Іін2	_	—	1	mA
Input High Voltage	All	VIH1, VIH2	2	-	V <sub>IN, max</sub>	Vdc
Logic Low (Module ON)						
Input low Current	All	IIL1, IIL2	—	—	20	μA
Input Low Voltage	All	VIL1, VIL2	-0.2	-	0.6	Vdc
Turn-On Delay and Rise Times						
(V_IN=V_IN, nom, $I_0{=}I_{0,max},V_0$ to within $\pm1\%$ of steady state)						
Case 1: On/Off input is enabled and then input power is applied (delay from instant at which $V_{IN} = V_{IN, min}$ until $V_0 = 10\%$ of $V_{0, set}$ )	All	Tdelay1, Tdelay2	_	2	_	msec

4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6A Output Current

Parameter	Device	Symbol	Min	Тур	Max	Unit
Case 2: Input power is applied for at least one second and then the On/Off input is enabled (delay from instant at which Von/Off is enabled until Vo = $10\%$ of Vo, set)	All	Tdelay1, Tdelay2	_	800	_	µsec
Output voltage Rise time (time for V $_0$ to rise from 10% of Vo, set to 90% of Vo, set)	All	Trise1, Trise2	_	6	_	msec
Output voltage overshoot ( $T_A = 25^{\circ}C$ $V_{IN} = V_{IN, min}$ to $V_{IN, max}$ , $I_O = I_{O, min}$ to $I_{O, max}$ ) With or without maximum external capacitance		Both Outputs			3.0	% V <sub>O, set</sub>

4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6AOutput Current

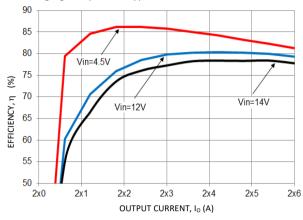
## Feature Specifications (cont.)

Parameter	Device	Symbol	Min	Тур	Max	Units
Over Temperature Protection (See Thermal Considerations section)	All	T <sub>ref</sub>		120		°C
Input Undervoltage Lockout						
Turn-on Threshold	All	Both Inputs			4.5	Vdc
Turn-off Threshold	All	Both Inputs			4.25	Vdc
Hysteresis	All	Both Inputs	0.15	0.2		Vdc
PGOOD (Power Good)						
Signal Interface Open Drain, $V_{supply} \leq 5VDC$						
Overvoltage threshold for PGOOD ON	All	Both Outputs		108.33		%V <sub>O, set</sub>
Overvoltage threshold for PGOOD OFF	All	Both Outputs		112.5		%V <sub>O, set</sub>
Undervoltage threshold for PGOOD ON	All	Both Outputs		91.67		%V <sub>O, set</sub>
Undervoltage threshold for PGOOD OFF	All	Both Outputs		87.5		%V <sub>O, set</sub>
Pulldown resistance of PGOOD pin	All	Both Outputs		40	70	Ω
Sink current capability into PGOOD pin	All	Both Outputs			5	mA

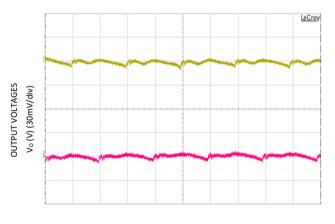
4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6A Output Current

### **Characteristic Curves**

The following figures provide typical characteristics for the 2 × 6A Analog Dual MicroDlynx<sup>™</sup> at 0.6Vo and 25°C.

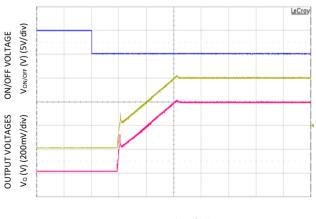






TIME, t (1µs/div)

Figure 3. Typical output ripple and noise ( $C_0$ = 2×4.7nF+2×47uF ceramic, VIN = 12V, Io = Io1,max, Io2,max, ).



TIME, t (2ms/div)

Figure 5. Typical Start-up Using On/Off Voltage (Vin=12V, Io = Io1,max, Io2,max,).

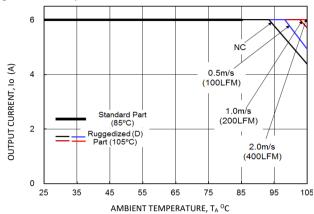
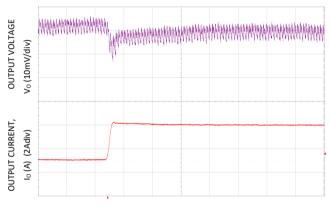
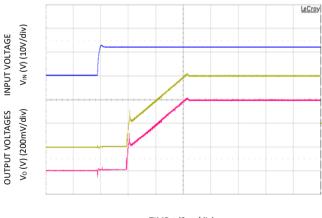


Figure 2. Derating Output Current versus Ambient Temperature and Airflow.



#### TIME, t (20µs /div)

Figure 4. Transient Response to Dynamic Load Change from 50% to 100% on one output at 12Vin, Cout=3x47uF+3x330uF, CTune=12nF, RTune= $300\Omega$ 



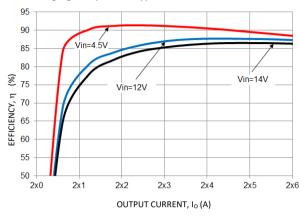
TIME, t (2ms/div)

Figure 6. Typical Start-up Using Input Voltage (VIN = 12V, Io = Io1,max, Io2,max,).

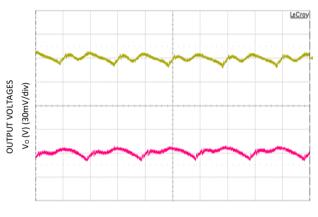
4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6AOutput Current

#### **Characteristic Curves**

The following figures provide typical characteristics for the 2 × 6A Analog Dual MicroDlynx<sup>™</sup> at 1.2Vo and 25°C.







TIME, t (1µs/div)

Figure 9. Typical output ripple and noise ( $C_0$ = 2×4.7nF+2×47uF ceramic, VIN = 12V, Io = Io1,max, Io2,max).

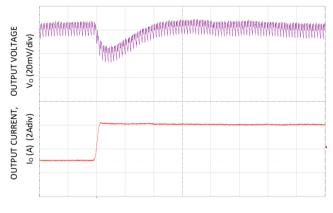


TIME, t (2ms/div)

Figure 1. Typical Start-up Using On/Off Voltage (VIN = 12V, Io = Io1,max, Io2,max).

6 NC OUTPUT CURRENT, Io (A) 4 0.5m/s (100LFM) 1.0m/s Standard Part (85ºC) (200LFM) 2 Ruggedized (D) Part (105ºC) 2.0m/s (400LFM) 0 25 35 45 55 65 75 85 95 105 AMBIENT TEMPERATURE, TA OC

Figure 8. Derating Output Current versus Ambient Temperature and Airflow.



TIME, t (20µs /div)

Figure 10. Transient Response to Dynamic Load Change on one output from 50% to 100% at 12Vin, Cout = 3x47uF + 2x330uF, CTune = 2700pF & RTune =  $300\Omega$ 



TIME, t (2ms/div)

Figure 12. Typical Start-up Using Input Voltage (VIN = 12V, Io = Io1,max, Io2,max).

4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6A Output Current

#### **Characteristic Curves**

The following figures provide typical characteristics for the 2 × 6A Analog Dual MicroDlynx<sup>™</sup> at 1.8Vo and 25°C.

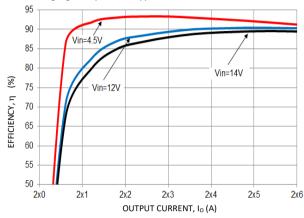
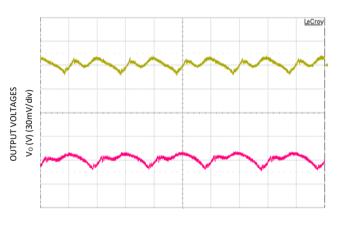
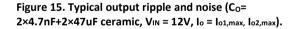
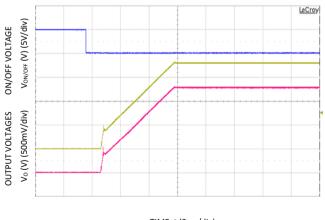


Figure 13. Converter Efficiency versus Output Current.



TIME, t (1µs/div)





TIME, t (2ms/div)

Figure 17. Typical Start-up Using On/Off Voltage ( $V_{IN}$  = 12V,  $I_0$  =  $I_{01,max}$ ,  $I_{02,max}$ ).

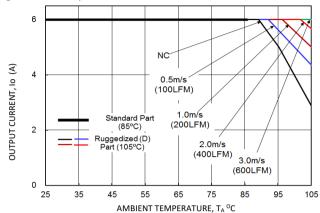
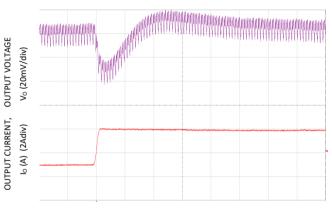


Figure 14. Derating Output Current versus Ambient Temperature and Airflow.



TIME, t (20µs /div)

Figure 16. Transient Response to Dynamic Load Change on one output from 50% to 100% at 12Vin, Cout = 3x47uF+1x330uF, CTune = 1800pF & RTune =  $300\Omega$ 

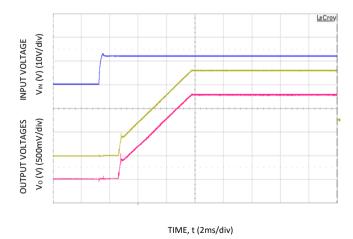


Figure 18. Typical Start-up Using Input Voltage (VIN = 12V, I₀ = I₀1,max, I₀2,max).

4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6AOutput Current

#### **Characteristic Curves**

The following figures provide typical characteristics for the 2 × 6A Analog Dual MicroDlynx<sup>™</sup> at 2.5Vo and 25°C.

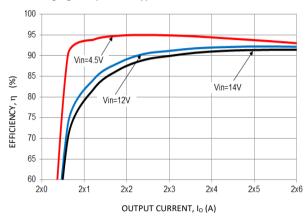
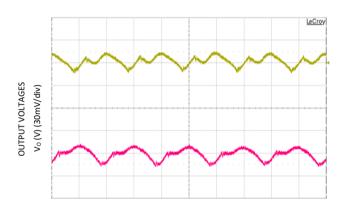
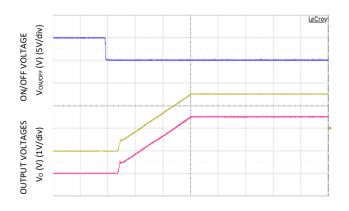


Figure 19. Converter Efficiency versus Output Current.



TIME, t (1µs/div)

Figure 21. Typical output ripple and noise ( $C_0$ = 2x4.7nF+2x47uF ceramic, VIN = 12V, Io = Io1,max, Io2,max).



TIME, t (2ms/div)

Figure 23. Typical Start-up Using On/Off Voltage (VIN = 12V, Io = Io1,max, Io2,max).

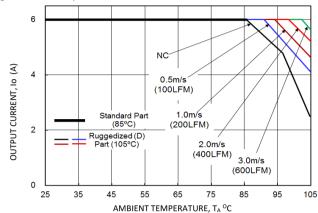
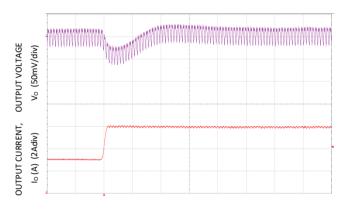
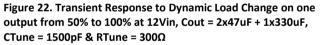
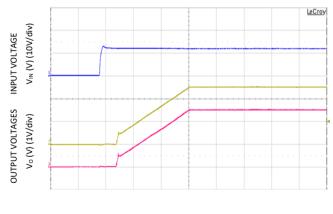


Figure 20. Derating Output Current versus Ambient Temperature and Airflow.









TIME, t (2ms/div)

Figure 24. Typical Start-up Using Input Voltage (VIN = 12V, Io = Io1,max, Io2,max).

GE

4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6A Output Current

#### **Characteristic Curves**

The following figures provide typical characteristics for the 2 × 6A Analog Dual MicroDlynx<sup>™</sup> at 3.3Vo and 25°C.

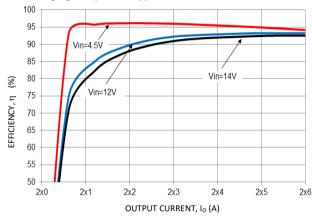
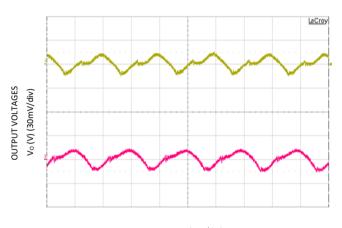
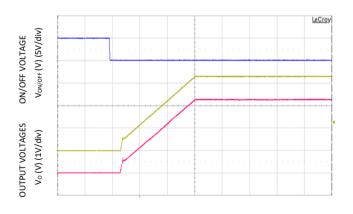


Figure 25. Converter Efficiency versus Output Current.



TIME, t (1µs/div)

Figure 27. Typical output ripple and noise ( $C_0$ = 2x4.7nF+2x47uF ceramic, VIN = 12V, Io = Io1,max, Io2,max).



TIME, t (2ms/div)

Figure 29. Typical Start-up Using On/Off Voltage ( $V_{IN} = 12V$ ,  $I_0 = I_{01,max}$ ,  $I_{02,max}$ ).

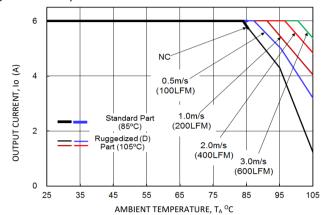
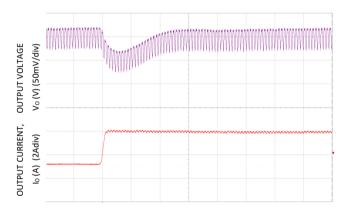
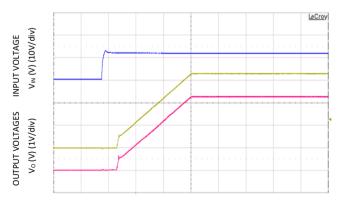


Figure 26. Derating Output Current versus Ambient Temperature and Airflow.



TIME, t (20µs /div)

Figure 28 Transient Response to Dynamic Load Change on one output from 50% to 100% at 12Vin, Cout = 2x47uF+1x330uF, CTune = 1200pF & RTune =  $300\Omega$ 



#### TIME, t (2ms/div)

Figure 30. Typical Start-up Using Input Voltage (VIN = 12V, Io = Io1,max, Io2,max).

4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6AOutput Current

### **Characteristic Curves**

The following figures provide typical characteristics for the 2 × 6A Analog Dual MicroDlynx<sup>™</sup> at 5Vo and 25°C.

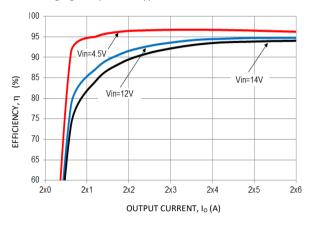
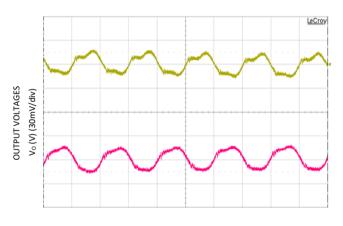
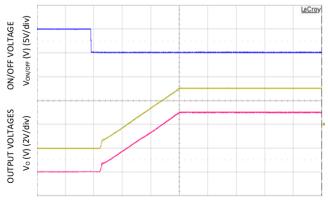


Figure 31. Converter Efficiency versus Output Current.



TIME, t (1µs/div)

Figure 33. Typical output ripple and noise ( $C_0 = 2 \times 4.7 nF + 2 \times 47 uF$  ceramic,  $V_{IN} = 12V$ ,  $I_0 = I_{01,max}$ ,  $I_{02,max}$ ).



TIME, t (2ms/div)

Figure 35. Typical Start-up Using On/Off Voltage ( $V_{IN}$  = 12V,  $I_0$  =  $I_{01,max}$ ,  $I_{02,max}$ ).

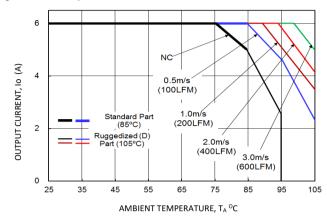


Figure 32. Derating Output Current versus Ambient Temperature and Airflow.

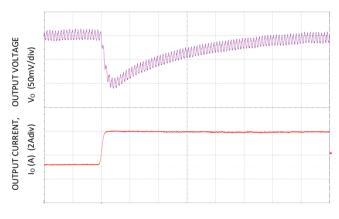
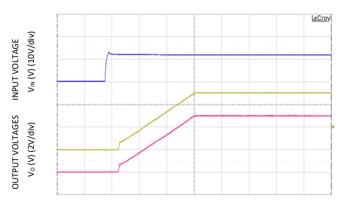




Figure 34. Transient Response to Dynamic Load Change on one output from 50% to 100% at 12Vin, Cout = 4x47uF, CTune = 470pF & RTune =  $300\Omega$ 



TIME, t (2ms/div)

Figure 36. Typical Start-up Using Input Voltage (VIN = 12V, I₀ = I₀1,max, I₀2,max).

4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6A Output Current

### **Design Considerations**

#### **Input Filtering**

The 2 × 6A Analog Dual MicroDlynx<sup>TM</sup> module should be connected to a low ac-impedance source. A highly inductive source can affect the stability of the module. An input capacitance must be placed directly adjacent to the input pin of the module, to minimize input ripple voltage and ensure module stability.

To minimize input voltage ripple, ceramic capacitors are recommended at the input of the module. Figure 37 shows the input ripple voltage for various output voltages at2 x 6A of load current with  $2x22 \ \mu$ F or  $4x22 \ \mu$ F ceramic capacitors and an input of 12V.

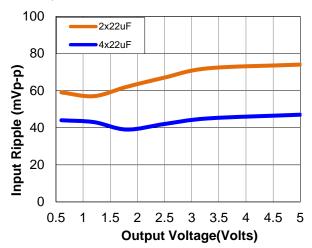


Figure 37. Input ripple voltage for various output voltages with  $2x22 \ \mu$ F or  $4x22 \ \mu$ F ceramic capacitors at the input (2 x 6A load). Input voltage is 12V. Scope BW: 20MHz

#### **Output Filtering**

These modules are designed for low output ripple voltage and will meet the maximum output ripple specification with 0.1  $\mu F$  ceramic and 22  $\mu F$  ceramic capacitors at the output of the module. However, additional output filtering may be required by the system designer for a number of reasons. First, there may be a need to further reduce the output ripple and noise of the module. Second, the dynamic response characteristics may need to be customized to a particular load step change.

To reduce the output ripple and improve the dynamic response to a step load change, additional capacitance at the output can be used. Low ESR polymer and ceramic capacitors are recommended to improve the dynamic response of the module. Figure 38 provides output ripple information for different external capacitance values at various Vo and a full load current of 2 x 6A. For stable operation of the module, limit the capacitance to less than the maximum output capacitance as specified in the electrical specification table. Optimal performance of the module can be achieved by using the Tunable Loop<sup>™</sup> feature described later in this data sheet.

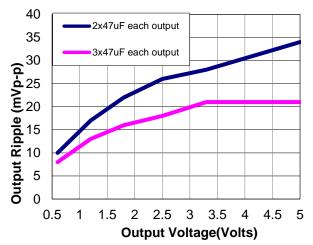


Figure 38. Output ripple voltage for various output voltages with total external 4x47  $\mu$ F or 6x47  $\mu$ F ceramic capacitors at the output (2 x 6A load). Input voltage is 12V. Scope BW: 20MHz

## **Safety Considerations**

For safety agency approval the power module must be installed in compliance with the spacing and separation requirements of the end-use safety agency standards, i.e., UL ANSI/UL\* 62368-1 and CAN/CSA+ C22.2 No. 62368-1 Recognized, DIN VDE 0868-1/A11:2017 (EN62368-1:2014/A11:2017).

For the converter output to be considered meeting the requirements of safety extra-low voltage (SELV), the input must meet SELV requirements. The power module has extra-low voltage (ELV) outputs when all inputs are ELV.

The input to these units is to be provided with a fast-acting fuse with a maximum rating of 15 A in the positive input lead.

4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6AOutput Current

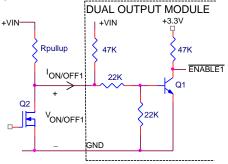
### **Analog Feature Descriptions**

#### **Remote On/Off**

The2 × 6A Analog Dual MicroDlynx<sup>™</sup> power modules feature an On/Off pin for remote On/Off operation. Two On/Off logic options are available. In the Positive Logic On/Off option, (device code suffix "4" - see Ordering Information), the module turns ON during a logic High on the On/Off pin and turns OFF during a logic Low. With the Negative Logic On/Off option, (no device code suffix, see Ordering Information), the module turns OFF during logic High and ON during logic Low. The On/Off signal should be always referenced to ground. For either On/Off logic option, leaving the On/Off pin disconnected will turn the module ON when input voltage is present.

For positive logic modules, the circuit configuration for using the On/Off pin is shown in Figure 39. For negative logic On/Off modules, the circuit configuration is shown in Fig. 40.

#### Output 1



#### Output 2

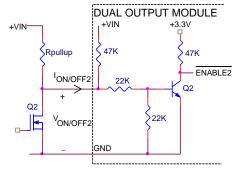


Figure 39. Circuit configuration for using positive On/Off logic.

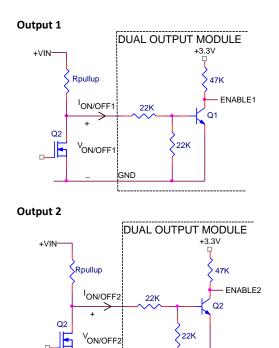


Figure 40. Circuit configuration for using negative On/Off logic.

GND

#### **Monotonic Start-up and Shutdown**

п-

The module has monotonic start-up and shutdown behavior for any combination of rated input voltage, output current and operating temperature range.

#### Startup into Pre-biased Output

The module can start into a prebiased output on either or both outputs as long as the prebias voltage is 0.5V less than the set output voltage.

#### Analog Output Voltage Programming

The output voltage of each output of the module shall be programmable to any voltage from 0.6dc to 5.5Vdc by connecting a resistor between the 2 Trims and SIG\_GND pins of the module. Certain restrictions apply on the output voltage set point depending on the input voltage. These are shown in the Output Voltage vs. Input Voltage Set Point Area plot in Fig. 1. The Upper Limit curve shows that for output voltages lower than 1V, the input voltage must be lower than the maximum of 14.4V. If the module can operate at 14.4V below 1V then that is preferable over the existing upper curve. The Lower Limit curve shows that for output voltages higher than 0.6V, the input voltage needs to be larger than the minimum of 4.5V.

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4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6A Output Current

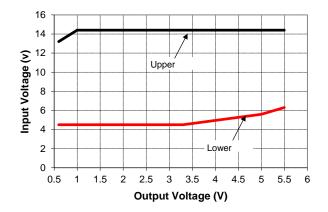
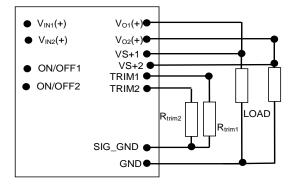


Figure 41. Output Voltage vs. Input Voltage Set Point Area plot showing limits where the output voltage can be set for different input voltages.



**Caution** – Do not connect SIG\_GND to GND elsewhere in the layout

Figure 42. Circuit configuration for programming output voltage using an external resistor.

Without an external resistor between Trim and SIG\_GND pins, each output of the module will be 0.6Vdc.To calculate the value of the trim resistor, *Rtrim* for a desired output voltage, should be as per the following equation:

$$Rtrim = \left[\frac{12}{(Vo - 0.6)}\right] k\Omega$$

Rtrim is the external resistor in  $k\boldsymbol{\Omega}$ 

*Vo* is the desired output voltage.

Table 1 provides Rtrim values required for some common output voltages.

-			
- T	ab	)le	1

V <sub>0, set</sub> (V)	Rtrim (KΩ)
0.6	Open
0.9	40
1.0	30
1.2	20
1.5	13.33

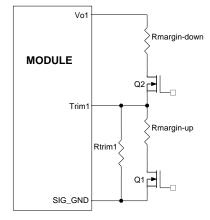
1.8	10
2.5	6.316
3.3	4.444
5.0	2.727

#### **Remote Sense**

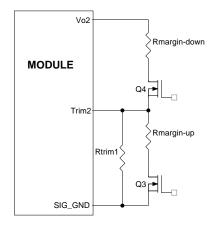
The power module has a Remote Sense feature to minimize the effects of distribution losses by regulating the voltage between the sense pins (VS+ and VS-) for each of the 2 outputs. The voltage drop between the sense pins and the VOUT and GND pins of the module should not exceed 0.5V. If there is an inductor being used on the module output, then the tunable loop feature of the module should be used to ensure module stability with the proposed sense point location. If the simulation tools and loop feature of the module are not being used, then the remote sense should always be connected before the inductor. The sense trace should also be kept away from potentially noisy areas of the board

#### **Analog Voltage Margining**

Output voltage margining can be implemented in the module by connecting a resistor, R<sub>margin-up</sub>, from the Trim pin to the ground pin for margining-up the output voltage and by connecting a resistor, R<sub>margin-down</sub>, from the Trim pin to output pin for margining-down. Figure 43 shows the circuit configuration for output voltage margining. The POL Programming Tool, available at www.gecriticalpower.com under the Downloads section, also calculates the values of R<sub>margin-up</sub> and R<sub>margin-down</sub> for a specific output voltage and % margin. Please consult your local GE technical representative for additional details.



4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6AOutput Current



# Figure 43. Circuit Configuration for margining Output voltage.

#### **Overcurrent Protection**

To provide protection in a fault (output overload) condition, the unit is equipped with internal current-limiting circuitry on both outputs and can endure current limiting continuously. At the point of current-limit inception, the unit enters hiccup mode. The unit operates normally once the output current is brought back into its specified range.

#### **Overtemperature Protection**

To provide protection in a fault condition, the unit is equipped with a thermal shutdown circuit. The unit will shut down if the overtemperature threshold of  $135^{\circ}C(typ)$  is exceeded at the thermal reference point  $T_{ref}$ . Once the unit goes into thermal shutdown it will then wait to cool before attempting to restart.

#### Input Undervoltage Lockout

At input voltages below the input undervoltage lockout limit, the module operation is disabled. The module will begin to operate at an input voltage above the undervoltage lockout turn-on threshold.

#### Synchronization

The module switching frequency can be synchronized to a signal with an external frequency within a specified range. Synchronization can be done by using the external signal applied to the SYNC pin of the module as shown in Fig. 45, with the converter being synchronized by the rising edge of the external signal. The Electrical Specifications table specifies the requirements of the external SYNC signal. If the SYNC pin is not used, the module should free run at the default switching frequency. If synchronization is not being used, connect the SYNC pin to SIG\_GND.

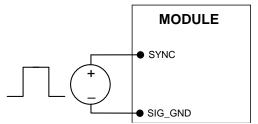


Figure 45. External source connections to synchronize switching frequency of the module.

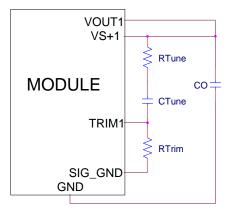
4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6A Output Current

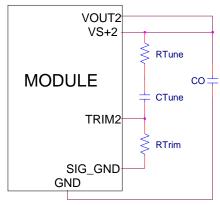
#### **Tunable Loop**<sup>™</sup>

The module has a feature that optimizes transient response of the module called Tunable Loop<sup>TM</sup>.

External capacitors are usually added to the output of the module for two reasons: to reduce output ripple and noise (see Figure 38) and to reduce output voltage deviations from the steady-state value in the presence of dynamic load current changes. Adding external capacitance however affects the voltage control loop of the module, typically causing the loop to slow down with sluggish response. Larger values of external capacitance could also cause the module to become unstable.

The Tunable Loop<sup>™</sup> allows the user to externally adjust the voltage control loop to match the filter network connected to the output of the module. The Tunable Loop<sup>™</sup> is implemented by connecting a series R-C between the VS+ and TRIM pins of the module, as shown in Fig. 47. This R-C allows the user to externally adjust the voltage loop feedback compensation of the module.





# Figure. 47. Circuit diagram showing connection of $R_{\text{TUNE}}$ and $C_{\text{TUNE}}$ to tune the control loop of the module.

Recommended values of  $R_{TUNE}$  and  $C_{TUNE}$  for different output capacitor combinations are given in Table 2. Table 2 shows the recommended values of  $R_{TUNE}$  and  $C_{TUNE}$  for different values of ceramic output capacitors up to 1000uF that might be needed for an application to meet output ripple and noise

requirements. Selecting  $R_{\text{TUNE}}$  and  $C_{\text{TUNE}}$  according to Table 2 will ensure stable operation of the module.

In applications with tight output voltage limits in the presence of dynamic current loading, additional output capacitance will be required. Table 3 lists recommended values of  $R_{TUNE}$  and  $C_{TUNE}$  in order to meet 2% output voltage deviation limits for some common output voltages in the presence of a 3A to 6A step change (50% of full load), with an input voltage of 12V.

Please contact your GE technical representative to obtain more details of this feature as well as for guidelines on how to select the right value of external R-C to tune the module for best transient performance and stable operation for other output capacitance values.

Table 2. General recommended values of of R<sub>TUNE</sub> and C<sub>TUNE</sub> for Vin=12V and various external ceramic capacitor combinations.

Со	2x47μF	4x47μF	6x47μF	10x47µF	20x47μF
R <sub>TUNE</sub>	300	300	300	300	300
CTUNE	220pF	1000pF	1500pF	2700pF	3900pF

Table 3. Recommended values of  $R_{\text{TUNE}}$  and  $C_{\text{TUNE}}$  to obtain transient deviation of 2% of Vout for a 6A step load with Vin=12V.

	Vo	/o 5V 3.3V		2.5V	1.8V	1.2V	0.6V
			•	2x47μF +	3x47μF +	3x47μF +	3x47μF +
	Со	4x47μF	330µF	1x330µF	1x330µF	2x330µF	2x330µF 3x330µF
			Polymer	Polymer	Polymer	Polymer	Polymer
	RTUNE	300	300	300	300	300	300
ſ	CTUNE	470pF	1500pF	1500pF	1800pF	2700pF	12nF
	Δv	69mV	31mV	30mV	27mV	18mV	9mV

Note: The capacitors used in the Tunable Loop tables are 47  $\mu$  F/2 m $\Omega$  ESR ceramic and 330  $\mu$  F/9 m $\Omega$  ESR polymer capacitors.

4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6AOutput Current

## **Thermal Considerations**

Power modules operate in a variety of thermal environments; however, sufficient cooling should always be provided to help ensure reliable operation.

Considerations include ambient temperature, airflow, module power dissipation, and the need for increased reliability. A reduction in the operating temperature of the module will result in an increase in reliability. The thermal data presented here is based on physical measurements taken in a wind tunnel. The test set-up is shown in Figure 49. The preferred airflow direction for the module is in Figure 50.

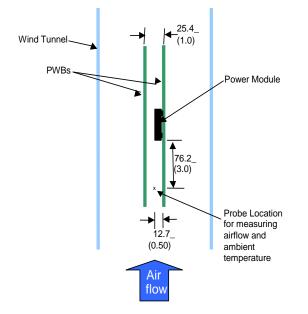


Figure 49. Thermal Test Setup.

The thermal reference points,  $T_{ref}$  used in the specifications are also shown in Figure 50. For reliable operation the temperatures at these points should not exceed 135°C. The output power of the module should not exceed the rated power of the module (Vo,set x Io,max).

Please refer to the Application Note "Thermal Characterization Process For Open-Frame Board-Mounted Power Modules" for a detailed discussion of thermal aspects including maximum device temperatures.

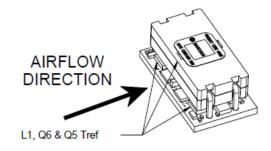


Figure 50. Preferred airflow direction and location of hotspot of the module (Tref).

4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6A Output Current

## **Shock and Vibration**

The ruggedized (-D version) of the modules are designed to withstand elevated levels of shock and vibration to be able to operate in harsh environments. The ruggedized modules have been successfully tested to the following conditions:

#### Non operating random vibration:

Random vibration tests conducted at 25C, 10 to 2000Hz, for 30 minutes each level, starting from 30Grms (Z axis) and up to 50Grms (Z axis). The units were then subjected to two more tests of 50Grms at 30 minutes each for a total of 90 minutes.

#### Operating shock to 40G per Mil Std. 810F, Method 516.4 Procedure I:

The modules were tested in opposing directions along each of three orthogonal axes, with waveform and amplitude of the shock impulse characteristics as follows:

All shocks were half sine pulses, 11 milliseconds (ms) in duration in all 3 axes.

Units were tested to the Functional Shock Test of MIL-STD-810, Method 516.4, Procedure I - Figure 516.4-4. A shock magnitude of 40G was utilized. The operational units were subjected to three shocks in each direction along three axes for a total of eighteen shocks.

#### Operating vibration per Mil Std 810F, Method 514.5 Procedure I:

The ruggedized (-D version) modules are designed and tested to vibration levels as outlined in MIL-STD-810F, Method 514.5, and Procedure 1, using the Power Spectral Density (PSD) profiles as shown in Table 7 and Table 8 for all axes. Full compliance with performance specifications was required during the performance test. No damage was allowed to the module and full compliance to performance specifications was required when the endurance environment was removed. The module was tested per MIL-STD-810, Method 514.5, Procedure I, for functional (performance) and endurance random vibration using the performance and endurance levels shown in Table 7 and Table 8 for all axes. The performance test has been split, with one half accomplished before the endurance test and one half after the endurance test (in each axis). The duration of the performance test was at least 16 minutes total per axis and at least 120 minutes total per axis for the endurance test. The endurance test period was 2 hours minimum per axis.

#### **Table 7: Performance Vibration Qualification - All Axes**

Frequency (Hz)	PSD Level (G2/Hz)	Frequency (Hz)	PSD Level (G2/Hz)	Frequency (Hz)	PSD Level (G2/Hz)				
10	1.14E-03	170	2.54E-03	690	1.03E-03				
30	5.96E-03	230	3.70E-03	800	7.29E-03				
40	40 9.53E-04 2		7.99E-04	890	1.00E-03				
50	2.08E-03	340	1.12E-02	1070	2.67E-03				
90	2.08E-03	370	1.12E-02	1240	1.08E-03				
110	7.05E-04	430	8.84E-04	1550	2.54E-03				
130	5.00E-03	490	1.54E-03	1780	2.88E-03				
140	140 8.20E-04		5.62E-04	2000	5.62E-04				

#### **Table 8: Endurance Vibration Qualification - All Axes**

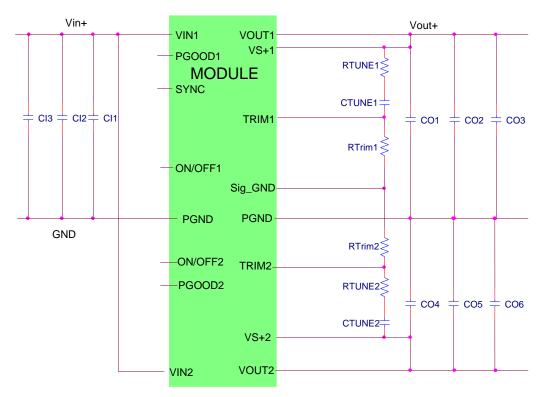
Frequency (Hz)	PSD Level (G2/Hz)	Frequency (Hz)	PSD Level (G2/Hz)	Frequency (Hz)	PSD Level (G2/Hz)
10	0.00803	170	0.01795	690	0.00727
30	0.04216	230	0.02616	800	0.05155
40	0.00674	290	0.00565	890	0.00709
50	0.01468	340	0.07901	1070	0.01887
90	0.01468	370	0.07901	1240	0.00764
110	0.00498	430	0.00625	1550	0.01795
130	0.03536	490	0.01086	1780	0.02035
140	0.0058	560	0.00398	2000	0.00398

4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6AOutput Current

## **Example Application Circuit**

## Requirements:

Vin:	12V
Vout:	1.8V
lout:	$2\times4.5A$ max., worst case load transient is from 3A to 4.5A
ΔVout:	1.5% of Vout (27mV) for worst case load transient
Vin, ripple	1.5% of Vin (180mV, p-p)



CI1	Decoupling cap - $4x0.1\mu$ F/16V, 0402 size ceramic capacitor
CI2	4x22µF/16V ceramic capacitor (e.g. Murata GRM32ER61C226KE20)
CI3	470μF/16V bulk electrolytic
CO1	Decoupling cap - $2x0.1\mu$ F/16V, 0402 size ceramic capacitor
CO2	3 x 47μF/6.3V ceramic capacitor (e.g. Murata GRM31CR60J476ME19)
CO3	NA
CO4	Decoupling cap - $2x0.1\mu$ F/16V, 0402 size ceramic capacitor
CO5	3 x 47μF/6.3V ceramic capacitor (e.g. Murata GRM31CR60J476ME19)
CO6	NA
CTune1	1500pF ceramic capacitor (can be 1206, 0805 or 0603 size)
RTune1	300 ohms SMT resistor (can be 1206, 0805 or 0603 size)
RTrim1	10k $\Omega$ SMT resistor (can be 1206, 0805 or 0603 size, recommended tolerance of 0.1%)
CTune2	1500pF ceramic capacitor (can be 1206, 0805 or 0603 size)
RTune2	300 ohms SMT resistor (can be 1206, 0805 or 0603 size)
RTrim2	10k $\Omega$ SMT resistor (can be 1206, 0805 or 0603 size, recommended tolerance of 0.1%)
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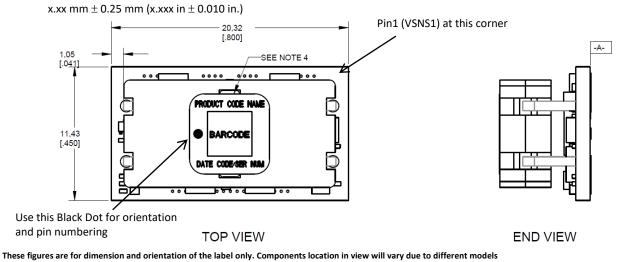
<u>Note</u>: The DATA, CLK and SMBALRT pins do not have any pull-up resistors inside the module. Typically, the SMBus master controller will have the pull-up resistors as well as provide the driving source for these signals.

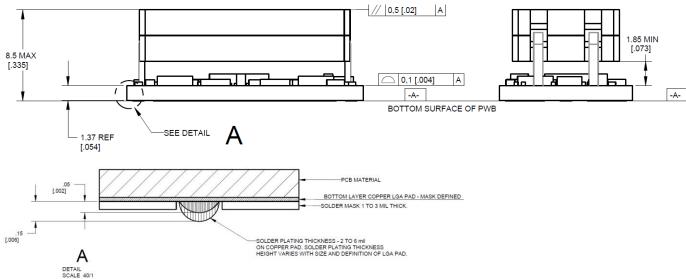
4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6A Output Current

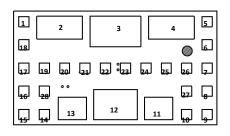
## **Mechanical Outline**

Dimensions are in millimeters and (inches).

Tolerances: x.x mm  $\pm$  0.5 mm (x.xx in.  $\pm$  0.02 in.) [unless otherwise indicated]







BOTTOM VIEW

PIN	FUNCTION	PIN	FUNCTION
1	VSNS1	15	NC
2	VOUT1	16	TRIM1
3	PGND	17	SIG_GND
4	VOUT2	18	TRIM2
5	VSNS2	19	SYNC
6	NC	20	PGND
7	NC	21	PGND
8	NC	22	PGND
9	ENABLE1	23	PGND
10	ENABLE2	24	PGND
11	VIN	25	PGND
12	PGND	26	PGND
13	VIN	27	PGOOD2
14	NC	28	PGOOD1

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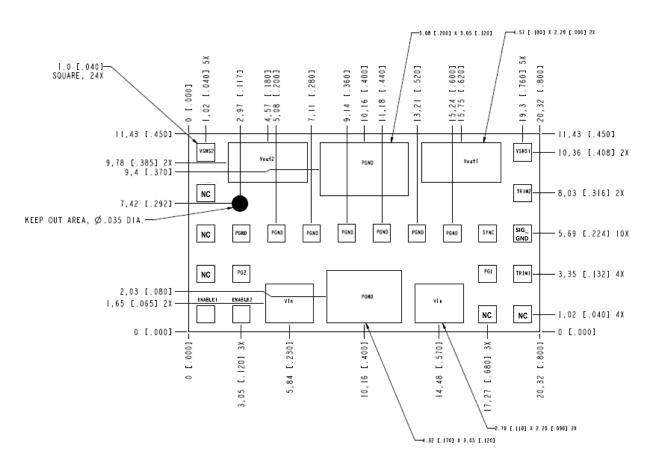
4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6AOutput Current

### **Recommended Pad Layout**

Dimensions are in millimeters and (inches).

Tolerances: x.x mm  $\pm$  0.5 mm (x.xx in.  $\pm$  0.02 in.) [unless otherwise indicated]

x.xx mm  $\pm$  0.25 mm (x.xxx in  $\pm$  0.010 in.)



PIN	FUNCTION	PIN	FUNCTION
1	VSNS1	15	NC
2	VOUT1	16	TRIM1
3	PGND	17	SIG_GND
4	VOUT2	18	TRIM2
5	VSNS2	19	SYNC
6	NC	20	PGND
7	NC	21	PGND
8	NC	22	PGND
9	ENABLE1	23	PGND
10	ENABLE2	24	PGND
11	VIN	25	PGND
12	PGND	26	PGND
13	VIN	27	PGOOD2
14	NC	28	PGOOD1

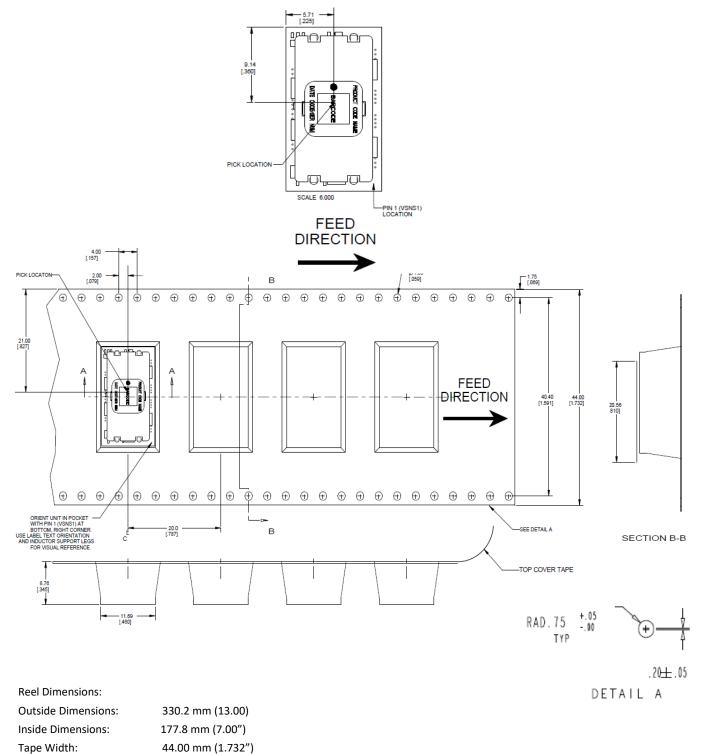
4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6A Output Current

## **Packaging Details**

The 12V Analog Dual MicroDlynx<sup>™</sup>2 × 6A modules are supplied in tape & reel as standard. Modules are shipped in quantities of 200 modules per reel.

All Dimensions are in millimeters and (in inches).

These figures are for dimension and orientation of the label only. Components location in view will vary due to different models Black Dot on the label is the orientation marker for locating Pin 1 (bottom right corner)



4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6AOutput Current

### **Surface Mount Information**

#### Pick and Place

The2 × 6A Analog Dual MicroDlynx<sup>™</sup> modules use an open frame construction and are designed for a fully automated assembly process. The modules are fitted with a label designed to provide a large surface area for pick and place operations. The label meets all the requirements for surface mount processing, as well as safety standards, and is able to withstand reflow temperatures of up to 300°C. The label also carries product information such as product code, serial number and the location of manufacture.

#### **Nozzle Recommendations**

The module weight has been kept to a minimum by using open frame construction. Variables such as nozzle size, tip style, vacuum pressure and placement speed should be considered to optimize this process. The minimum recommended inside nozzle diameter for reliable operation is 3mm. The maximum nozzle outer diameter, which will safely fit within the allowable component spacing, is 7 mm.

#### **Bottom Side / First Side Assembly**

This module is not recommended for assembly on the bottom side of a customer board. If such an assembly is attempted, components may fall off the module during the second reflow process.

#### **Lead Free Soldering**

The modules are lead-free (Pb-free) and RoHS compliant and fully compatible in a Pb-free soldering process. Failure to observe the instructions below may result in the failure of or cause damage to the modules and can adversely affect longterm reliability.

#### **Pb-free Reflow Profile**

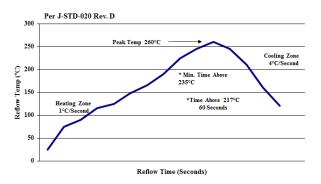
Power Systems will comply with J-STD-020 Rev. D (Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices) for both Pb-free solder profiles and MSL classification procedures. This standard provides a recommended forced-air-convection reflow profile based on the volume and thickness of the package (table 4-2). The suggested Pb-free solder paste is Sn/Ag/Cu (SAC). The recommended linear reflow profile using Sn/Ag/Cu solder is shown in Fig. 50. Soldering outside of the recommended profile requires testing to verify results and performance.

#### **MSL** Rating

The2 x 6A Analog Dual MicroDlynx<sup>TM</sup> modules have a MSL rating of 3

#### **Storage and Handling**

The recommended storage environment and handling procedures for moisture-sensitive surface mount packages is detailed in J-STD-033 Rev. A (Handling, Packing, Shipping and Use of Moisture/Reflow Sensitive Surface Mount Devices). Moisture barrier bags (MBB) with desiccant are required for MSL ratings of 2 or greater. These sealed packages should not be broken until time of use. Once the original package is broken, the floor life of the product at conditions of  $\leq$  30°C and 60% relative humidity varies according to the MSL rating (see J-STD-033A). The shelf life for dry packed SMT packages will be a minimum of 12 months from the bag seal date, when stored at the following conditions: < 40° C, < 90% relative humidity.



# Figure 51. Recommended linear reflow profile using Sn/Ag/Cu solder.

#### Post Solder Cleaning and Drying Considerations

Post solder cleaning is usually the final circuit-board assembly process prior to electrical board testing. The result of inadequate cleaning and drying can affect both the reliability of a power module and the testability of the finished circuit-board assembly. For guidance on appropriate soldering, cleaning and drying procedures, refer to *Board Mounted Power Modules: Soldering and Cleaning* Application Note (AN04-001).

4.5Vdc –14.4Vdc input; 0.6Vdc to 5.5Vdc output; 2 × 6A Output Current

### **Ordering Information**

Please contact your GE Sales Representative for pricing, availability and optional features.

#### Table 9. Device Codes

Device Code	Device Code Input Voltage Range		Output Current	On/Off Logic	Sequencing	Comcodes
UVXS0606A0X3-SRZ	4.5 – 14.4Vdc	0.6 – 5.5 Vdc	6A x 2	Negative	No	150038097
UVXS0606A0X43-SRZ	4.5 – 14.4Vdc	0.6 – 5.5 Vdc	6A x 2	Positive	No	150038110
UVXS0606A0X3-SRDZ	4.5 – 14.4Vdc	0.6 – 5.5 Vdc	6A x 2	Negative	No	150038111

#### Table 10. Coding Scheme

Package Identifier	Family	Sequencing Option	Input Voltage	Output current	Output voltage	On/Off logic	Remote Sense	Opt	ions	ROHS Compliance
U	v	х	S	0606A0	х		3	-SR	-D	z
P=Pico U=Micro M=Mega G=Giga	D=Dlynx Digital V = DLynx Analog.	T=with EZ Sequence X=without sequencing	Special: 4.5 – 14V	2 × 6A	X = programma ble output	4 = positive No entry = negative	3 = Remote Sense	S = Surface Mount R = Tape & Reel	D = 105C operating ambient, 40G operating shock as per MIL Std 810F	Z = ROHS6

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